

ABSTRACT OF THE DISCLOSURE

Plate positioning and processing method and apparatus are disclosed. A plate is conveyed in a predetermined first direction so that the plate is in contact with a pair of first positioning pins. The plate is laterally moved contacting with the first positioning pins until reference positions displaced from contacting positions of the plate with the first positioning pins contact with the first positioning pins. A predetermined first processing is applied to the plate. The plate subjected to the first processing is conveyed in a predetermined second direction so that the plate is in contact with a pair of second positioning pins in positions different from the reference positions of front edge of the plate. The plate contacting with the second positioning pins is laterally moved until the same positions as the reference positions contact with the second positioning pins.

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